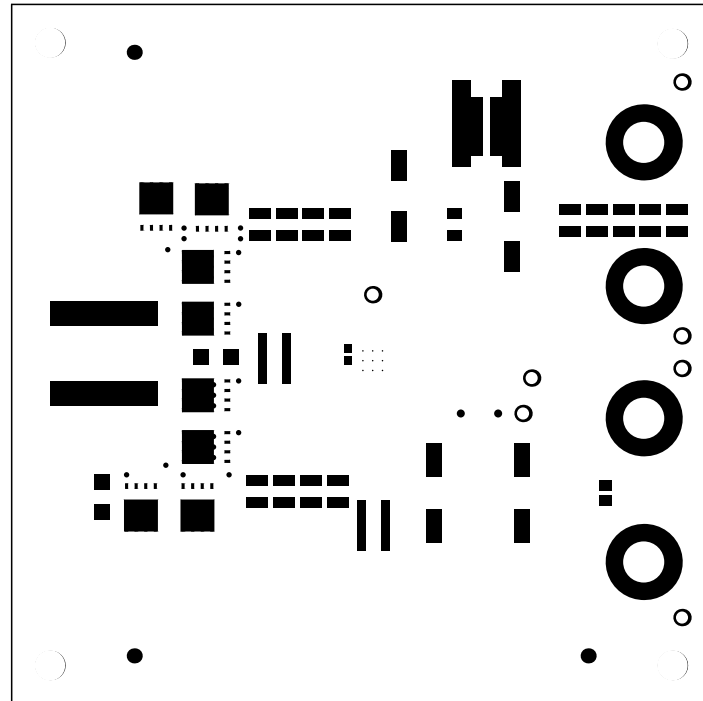
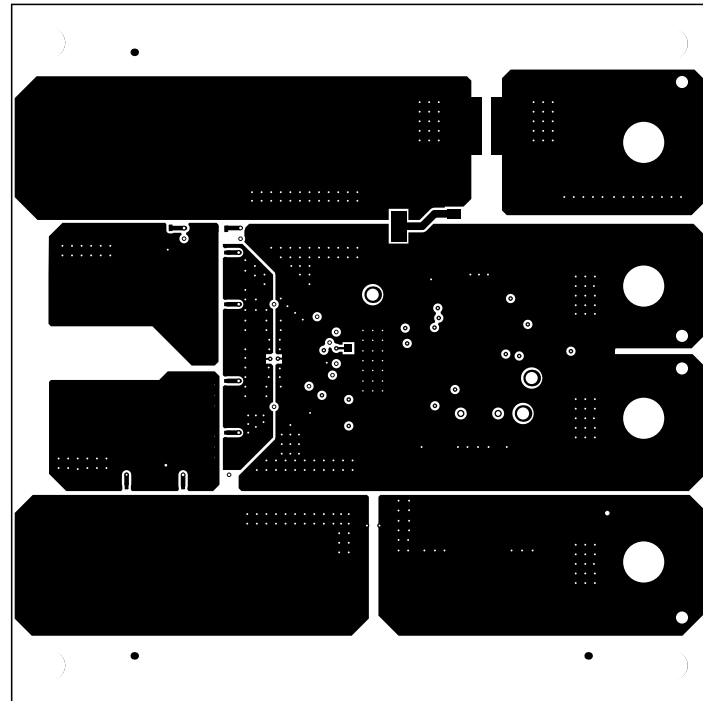


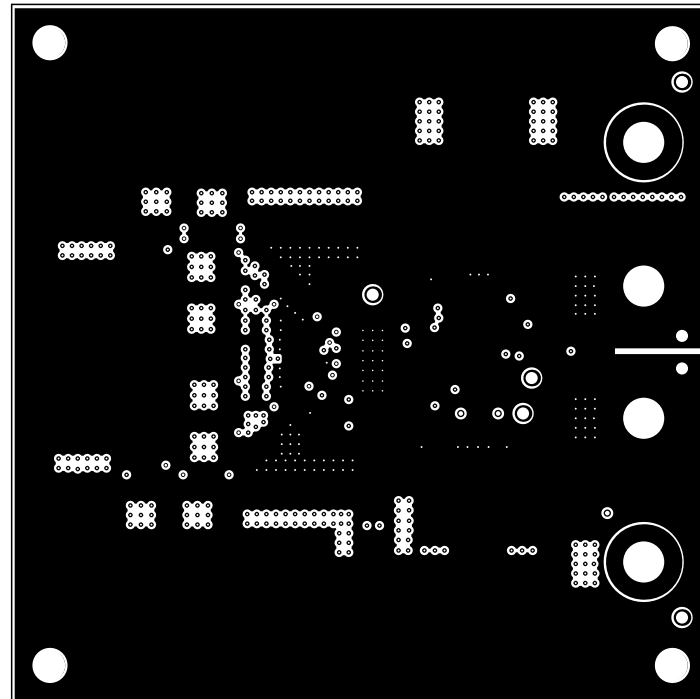
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 6/22/2017 10:04:50 AM	TEXAS INSTRUMENTS	



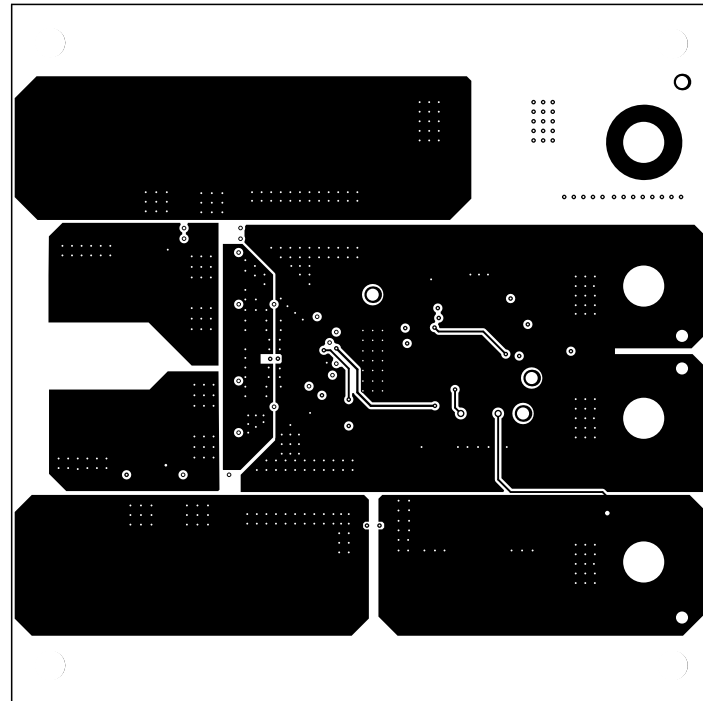
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 6/22/2017 10:04:54 AM	TEXAS INSTRUMENTS	



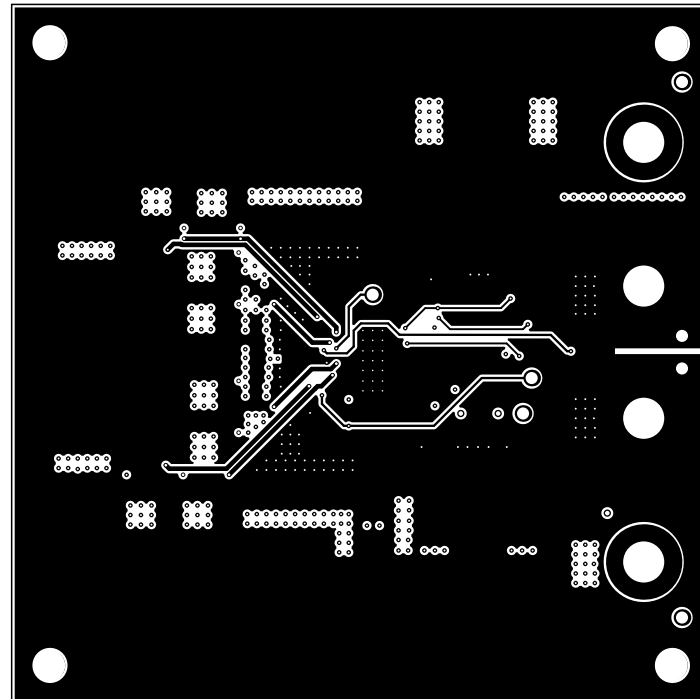
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 6/22/2017 10:04:59 AM	TEXAS INSTRUMENTS	



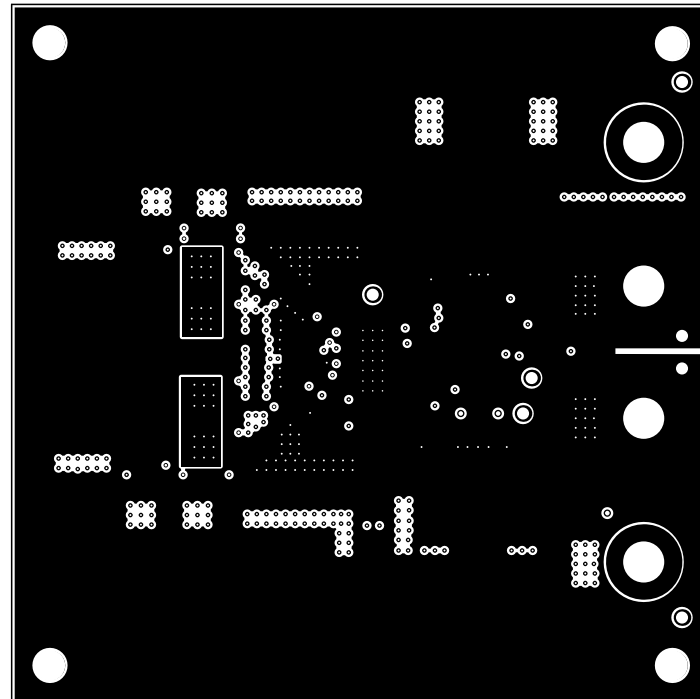
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1			
PLOT NAME = Signal Layer 1	GENERATED : 6/22/2017 10:05:05 AM	TEXAS INSTRUMENTS	



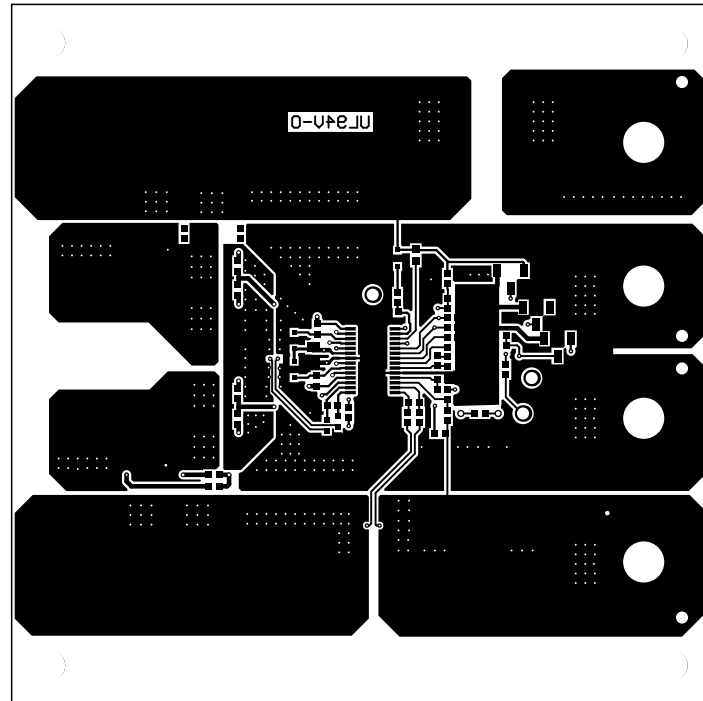
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2			
PLOT NAME = Signal Layer 2	GENERATED : 6/22/2017 10:05:10 AM	TEXAS INSTRUMENTS	



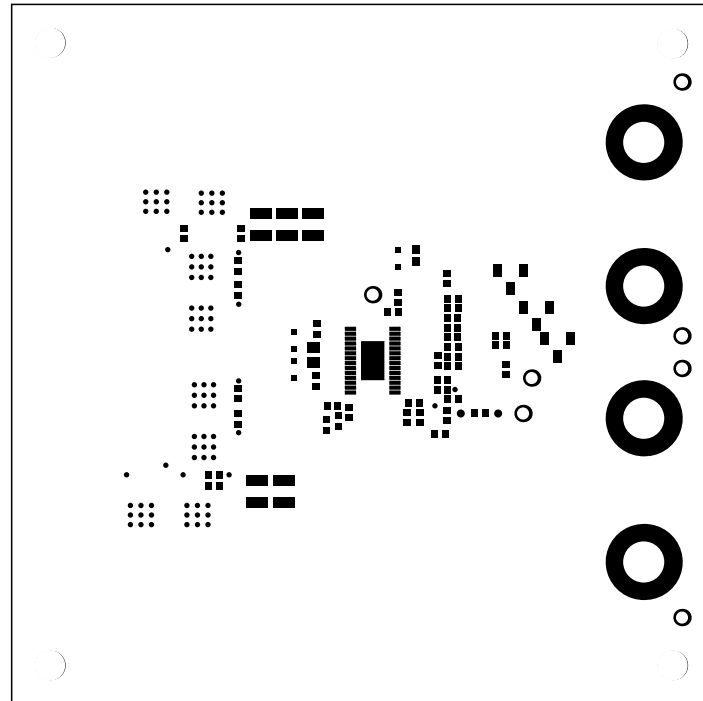
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = MidLayer3			
PLOT NAME = Signal Layer 3	GENERATED : 6/22/2017 10:05:16 AM	TEXAS INSTRUMENTS	



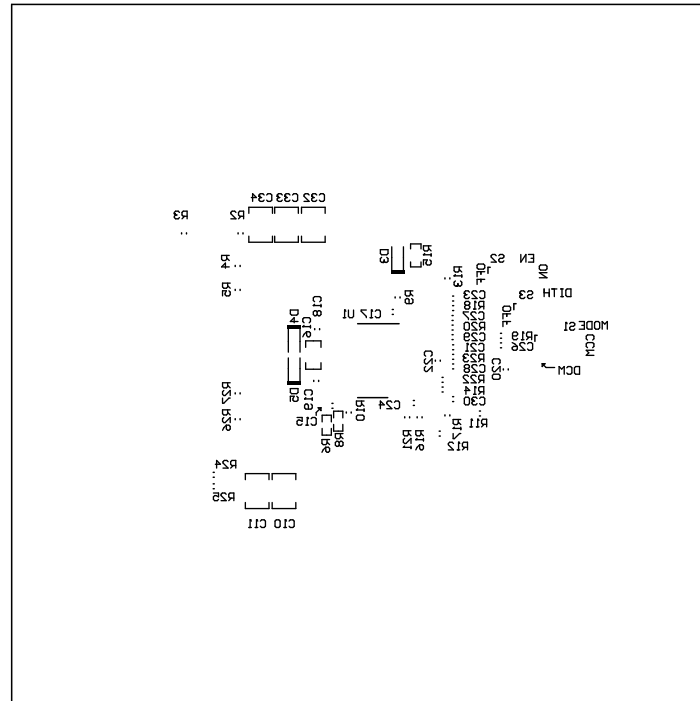
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = MidLayer 4			
PLOT NAME = Signal Layer 4	GENERATED : 6/22/2017 10:05:23 AM	TEXAS INSTRUMENTS	



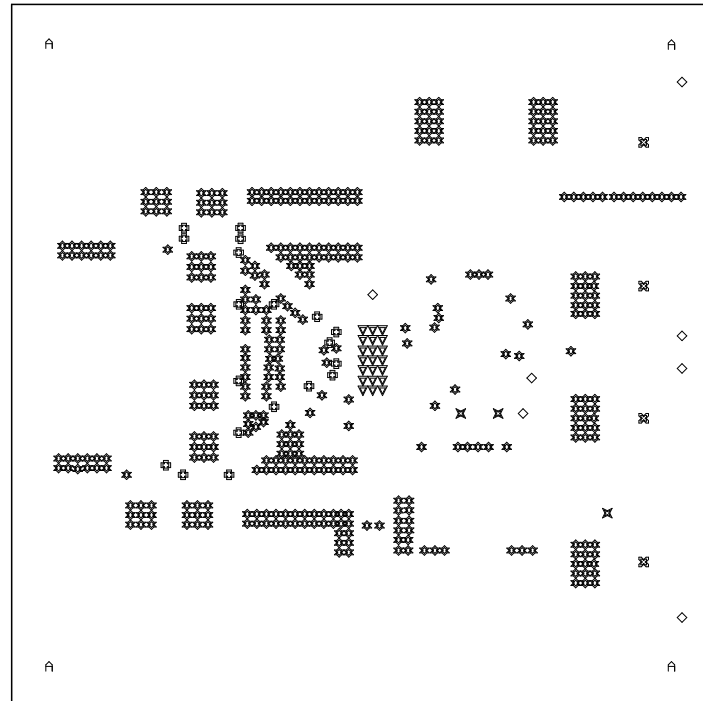
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 6/22/2017 10:05:31 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 6/22/2017 10:05:38 AM	TEXAS INSTRUMENTS	

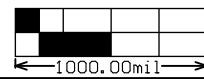
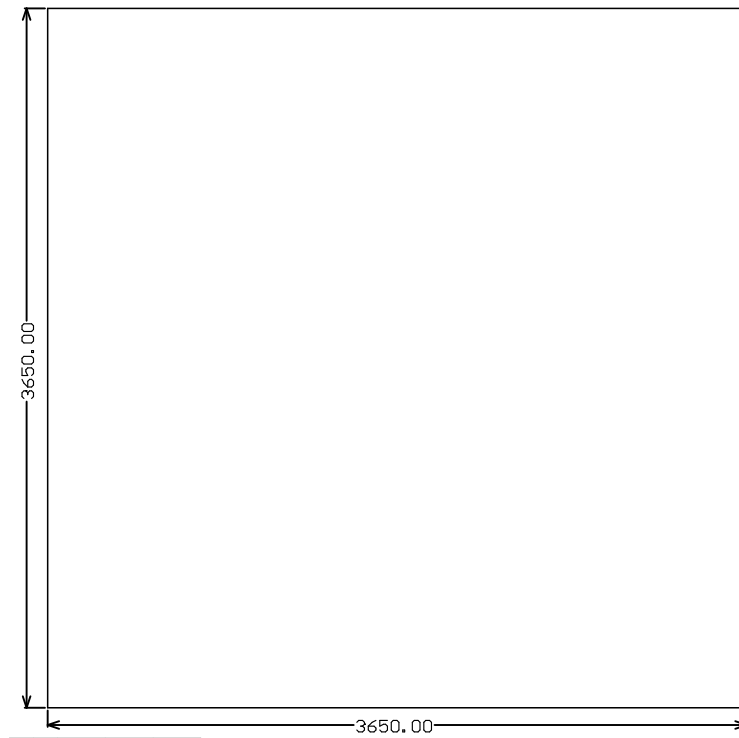


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 6/22/2017 10:05:46 AM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type
▽	21	7.87mil (0.200mm)	PTH	Round
*	393	10.00mil (0.254mm)	PTH	Round
⊕	19	14.00mil (0.356mm)	PTH	Round
✕	3	24.00mil (0.610mm)	PTH	Round
◇	7	63.00mil (1.600mm)	PTH	Round
⌘	4	159.00mil (4.039mm)	NPTH	Round
⊗	4	214.57mil (5.450mm)	PTH	Round
451 Total				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 6/22/2017 10:05:54 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU601348	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 6/22/2017 10:06:02 AM	TEXAS INSTRUMENTS	

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